3.3V, 1-port, SATA Gen 3i ReDriver™ with Adjustable Equalization/Pre-Emphasis
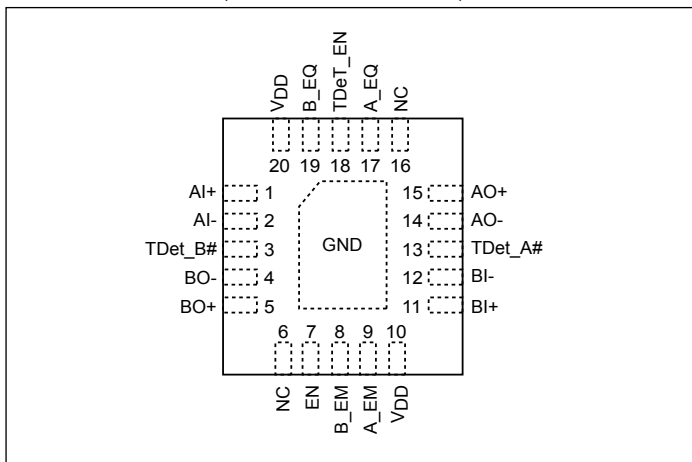
Features

➔ Supports SATA Gen 3i.

➔ Two 6Gbps differential signal pairs

➔ 100Ω Differential CML I/O's

➔ Input signal level detect and squelch for each channel

➔ OOB Support

➔ Automatic HDD Rate detection for output swing/emphasis setting

➔ Termination detect indication
   ▫ Power saving mode control to Host or HDD

➔ Adjustable Receiver Equalization

➔ Selectable Output Pre-emphasis and Swing Control

➔ High impedance I/O termination in standby mode

➔ ESD +/-8kV

➔ Low Power Operation: 254mW typical

➔ Auto-Slumber Mode: 36mW typical

➔ HDD unplugged: 3.6mW

➔ Power down Stand-by Mode: 0.7mW max

➔ Supply Voltage: 3.3V ±10%

➔ Industrial Temperature Range: -40°C to 85°C

➔ Packaging: 20-TQFN (4x4mm)

Applications

➔ Notebook, desktop, docking station, Set Top Box, Server Workstation, Data Storage

Description

The PI3EQX6741ST is a low power, signal SATA Gen 3i 6Gbps ReDriver™. The device provides programmable equalization and output emphasis, to optimize performance over a variety of physical mediums by reducing Inter-Symbol Interference. PI3EQX6741ST supports two 100Ω Differential CML data I/O's between the Protocol ASIC to a switch fabric, across a backplane, or to extend the signals across other distant data pathways on the user's platform.

The integrated equalization circuitry provides flexibilitywith signal integrity of the signal before the ReDriver.

A low-level input signal detection and output squelch function is provided for each channel. Each channel operates fully independently. When the channels are enabled (EN=1) and operating, that channels input signal level (on xI+/-) determines whether the output is active. If the input signal level of the channel falls below the active threshold level (Vth-) then the outputs are driven to the common mode voltage.

Termination Detect indication (TDet_A# or TDET_B#) provides indication when the load is connected ie HDD or Host. This can be used as control to go into power saving mode by either the host or HDD.

In addition to signal conditioning, when EN = 0, the device enters a low power standby mode.

Pin Diagram (Top Side View)

Block Diagram
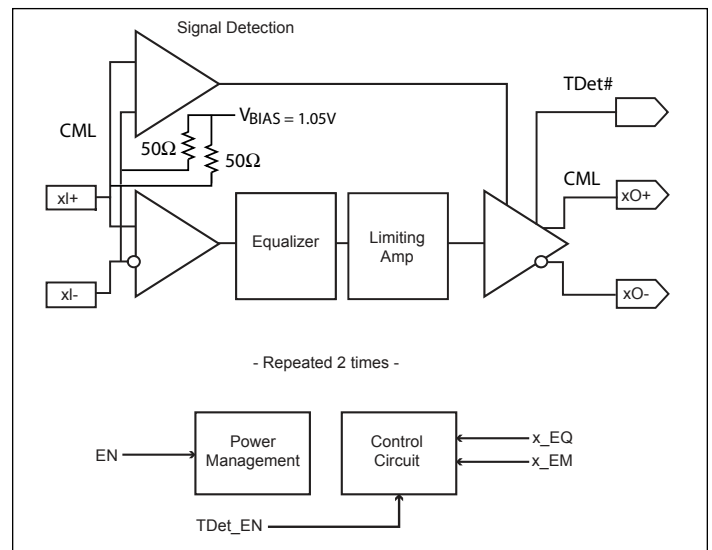
Pin Description

Standard Mode Pin #	Pin Name	Type	Description
9	A_EM	Input	Output emphasis adjustment for channel A. (See Configuration Table) Digital control with 200KΩ pull-up resistor.
17	A_EQ	Input	Channel A Equalization adjustment is active. (See Configuration Table) Tri-level input pin with 100KΩ pull-up and 100KΩ pull-down resistors.
1 2	AI+ AI-	Input	CML input forward channel A with internal 50Ω pull-up resistors connected to VBIAS (100Ω differential).
15 14	AO+ AO-	Output	CML output channel A with internal 50Ω pull-up resistors connected to VBIAS (100Ω differential).
8	B_EM	Input	Output emphasis adjustment for channel B. (See Configuration Table) Digital control with 200KΩ pull-up resistor.
19	B_EQ	Input	Tri-level input pin with 100KΩ pull-up and 100KΩ pull-down resistors. (See Configuration Table)
11 12	BI+ BI-	Input	CML input return channel B with internal 50KΩ pull-up, resistor connected to VBIAS (100Ω differential).
5 4	BO+ BO-	Output	Positive CML output channel B with internal 50Ω pull-up resistor connected to VBIAS (100Ω differential).
7	EN	Input	Chip Enable "High" provides normal operation. "Low" for power down mode. With internal 200KΩ pull-up resistor.
Center Pad	GND	GND	Supply ground.
10, 20	V$_{DD}$	Power	3.3V supply voltage ± 10%
3	TDet_B#	Output	Termination detect output for channel B-Active Low, open drain. Low: HDD Termination present. High: HDD Termination NOT present.
13	TDet_A#	Output	Termination detect output for channel A-Active Low, open drain. Low: HDD Termination present. High: HDD Termination NOT present.
18	TDet_EN	Input	Termination Detect Enable (200KΩ internal pull-up resistor) High: Enable Termination Detect for eSATA application or hot plug Device application Low: Disable Termination Detect for internal SATA application.
6, 16	NC		No Connection internally.

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Configuration Table - Output Pre-emphasis/Swing Setting

A_EM/B_EM	3 Gb/s	6 Gb/s
0	550mV pp	650mV pp
1	550mV pp + 3dB Pre-emphasis	650mV pp + 1.5dB Pre-emphasis

Configuration Table - Input Equalizer

A_EQ/B_EQ	1.5 Gb/s	3 Gb/s	6Gb/s
0	1 dB	2.5 dB	3 dB
floating	2.5 dB	5 dB	6 dB
1	4 dB	7.5 dB	9 dB

Termination Detect Feature:

Termination Detect is a power saving feature. The user can enable TDet_EN (set to High) for eSATA application as it would save more power when there is no external HDD connection. But for internal SATA application, TDet_EN should be set to LOW because internal HDD is always on and termination is always there.

When Redriver doesn't detect Host or HDD termination, there will be about 12us detect pulse width with 50us detect period at the output of ReDriver. Once the termination is detected, the detect period will change to about 40ms. Anyway when the signal is detected at the input of redriver, there will not be any detect pulse at both the output side of redriver.

Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature...−65°C to +150°C

Supply Voltage to Ground Potential.......................−0.5V to +4.6V

DC SIG Voltage ....−0.5V to V_{DD} +0.5V

Output Current .... -25mA to +25mA

Power Dissipation Continuous 500mW

Operating Temperature .... -40°C to +85°C

ESD, Human Body Model ....-8kV to 8kV

Note:

Stresses greater than those listed under MAXIMUM RAT-INGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

AC/DC Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.[1]	Max.	Units
V_{DD}	Power Supply Voltage		3.0		3.6	V
$P_{STANDBY}$	Supply Power, Standby	EN = 0		0.07	0.7	mW
P_{UNPLUG}	Supply Power, HDD unplugged	No HDD attached, TDet_EN = High		3.6	11	
$P_{SLUMBER}$	Supply Power, Slumber	TDet_EN = Low		36	50	
P_{ACTIVE}	Supply Power, Active	EN = 1 A/B_EM=0 $DIFF_{P-P} \geq V_{TH-SD}$		254	317	
$I_{DD-STANDBY}$	Supply Current Standby	EN = 0		0.02	0.2	mA
$I_{DD-UNPLUG}$	Supply Current, HDD unplugged	No HDD attached, TDet_EN = High		1	3	
$I_{DD-SLUMBER}$	Supply Current Slumber	TDet_EN = Low		11	14	
$I_{DD-ACTIVE}$	Supply Current Active	EN = 1, input = 600mVppd, A/B_EM=0		77	88	
tPD	Latency	From input to output		0.7		ns
CML Receiver Input						
Z_{RX-DC}	DC Input Impedance		40	50	60	Ohm
$Z_{RX-DIFF-DC}$	DC Differential Input Impedance		80	100	120	
$V_{RX-DIFFp-p}$	Differential Input Peak-to-peak Voltage		0.2		1.2	V
$V_{RX-CM-ACP}$	AC Peak Common Mode Input Voltage				150	mV
V_{TH-SD}	Signal detect Threshold	EN = 1	50		200[2]	mVppd

Note:

1. Typical values are at V_{DD} = 3.3V, T_A = 25°C ambient and maximum loading.

2. Using Compliance test at 1.5Gbps, 3Gbps and 6Gbps. Also using OOB (OOB is formed by ALIGNp primitive or D24.3) test patterns at 1.5Gbps.
   The ALIGN primitive (K28.5+D10.2+D27.3 = 0011111010+0101010101+0010011100). The D24.3 = 00110011001100110011.

AC/DC Electrical Characteristics (CML Receiver Input continued)

Symbol	Parameter	Conditions		Min.	Typ.[1]	Max.	Units
RL_{dd11_RX}	RX differential mode return loss	75MHz-300MHz 300MHz-600MHz 600MHz-1.2GHz 1.2GHz-2.4GHz 2.4GHz-3.0GHz 3.0 GHz-5.0GHz		18 14 10 8 3 1			dB
RL_{cc11_RX}	RX common mode return loss	150MHz – 300MHz 300MHZ – 600MHz 600MHz – 1.2GHz 1.2GHz – 2.4GHz 2.4GHz – 3.0GHz 3.0GHz – 5.0GHz		3 5 2 2 1 1			dB
RL_{dc11_RX}	RX impedance balance	150MHz – 300MHz 300MHz – 600MHz 600MHz – 1.2GHz 1.2GHz – 2.4GHz 2.4GHz – 3.0GHz 3.0GHz – 5.0GHz		30 30 20 10 4 4			dB

CML Transmitter Output (100Ω differential)[3]

Symbol	Parameter	Conditions		Min.	Typ.[1]	Max.	Units
$Z_{TX-DIFF-DC}$	DC Differential TX Impedance			80	100	120	Ohm
$V_{TX-DIFFp-p}$	Differential Peak-to-peak Output Voltage	$V_{TX-DIFFp-p} = 2 * \mid V_{TX-D}$	SATA2	450		700	mV
			SATA3	550		750	
V_{TX-C}	Common-Mode Voltage	$\mid V_{TX-D+} + V_{TX-D-}\mid/2$		0.5		1.2	V
t_F, t_R	Transition Time	20% to 80% [3] 0dB Pre-emphasis		40		150	ps
V_{amp_bal}	TX amplitude imbalance	3G only; HFTP, MFTP				10	%
T_{skew}	TX differential skew	1.5G and 3G; HFTP, MFTP				20	ps
V_{cm_ac}	TX AC common mode voltage	3G only; MFTP				50	mVpp
$V_{TX-Pre-Ratio-max}$	Max TX Pre-emphasis Level				3		dB
					1.5		
RL_{dd11_TX}	TX differential mode return loss	150MHz – 300MHz 300MHz – 600MHz 600MHz – 1.2GHz 1.2GHz – 2.4GHz 2.4GHz – 3.0GHz 3.0 GHz – 5.0GHz		14 8 6 6 3 1			dB
C_{TX}	AC Coupling Capacitor			2	4.7	12	nF
T_J	Total Jitter	FR4 Input Trace	18"			0.16	UI
			36"			0.24	
D_J	Deterministic Jitter	FR4 Input Trace	18"			0.11	UI
			36"			0.19	

Note:
3. Recommended output coupling capacitor is 4.7nF to 12nF (on each output)
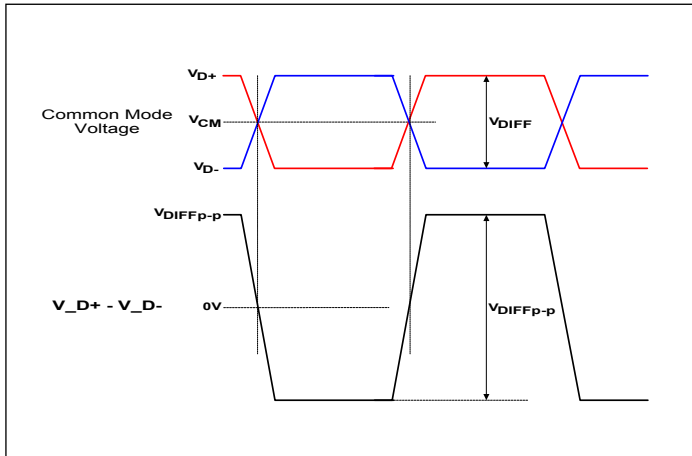
AC/DC Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.[1]	Max.	Units
RL_{cc11_TX}	TX common mode return loss	150MHz – 300MHz 300MHz – 600MHz 600MHz – 1.2GHz 1.2GHz – 2.4GHz 2.4GHz – 3.0GHz 3.0 GHz – 5.0GHz	5 5 2 2 1 1			dB
RL_{dc11_TX}	TX impedance balance	150MHz – 300MHz 300MHz – 600MHz 600MHz – 1.2GHz 1.2GHz – 2.4GHz 2.4GHz – 3.0GHz 3.0 GHz – 5.0GHz	30 20 10 10 4 4			dB
LVCMOS Control Pins						
V_{IH}	Input High Voltage (Bi-Level)		$0.65 \times V_{DD}$			V
V_{IL}	Input Low Voltage (Bi-Level)				$0.35 \times V_{DD}$	V
I_{IH}	Input High Current				100	µA
I_{IL}	Input Low Current		-100			µA
V_{OL}	DC Output Logic Low	$I_{OL} = 4\,mA$			0.4	V
V_{IH}	Input High Voltage (Tri-Level)		$0.8 \times V_{DD}$			V
V_{IL}	Input Low Voltage (Tri-Level)				$0.2 \times V_{DD}$	V

Auto Slumber Mode Entry/Exit Time

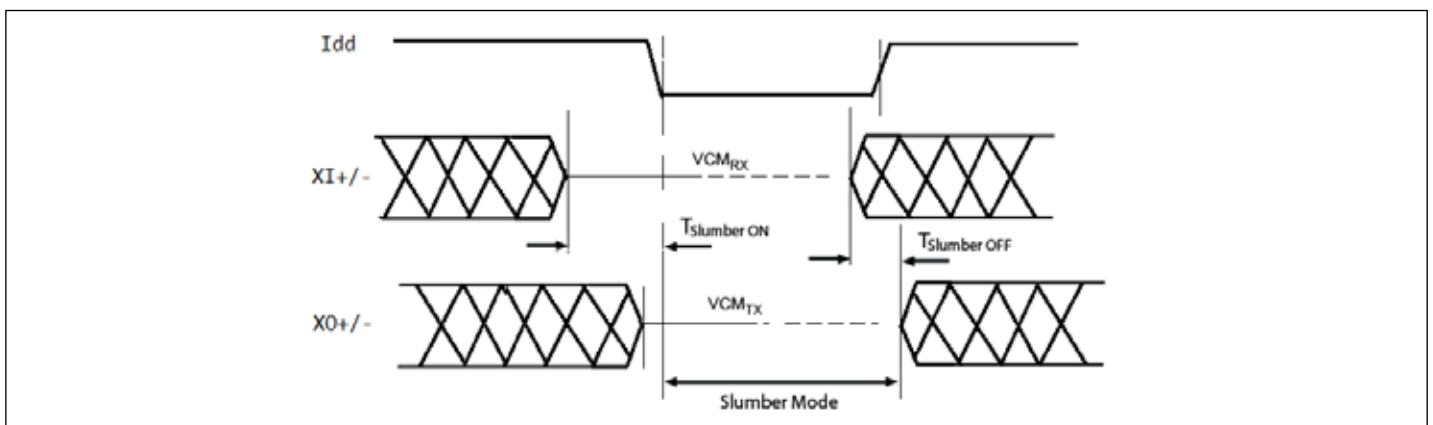| Symbol	Parameter	Conditions	Min.	Typ.[1]	Max.	Units
$T_{SlumberON}$	Entry time to Slumber Mode	Electrical Idle at Input (See Figure)		10	20	µS
$T_{SlumberOFF}$	Exit time from Slumber Mode	After first signal activity (See Figure)		6	20	ns

**Definition of Differential Voltage
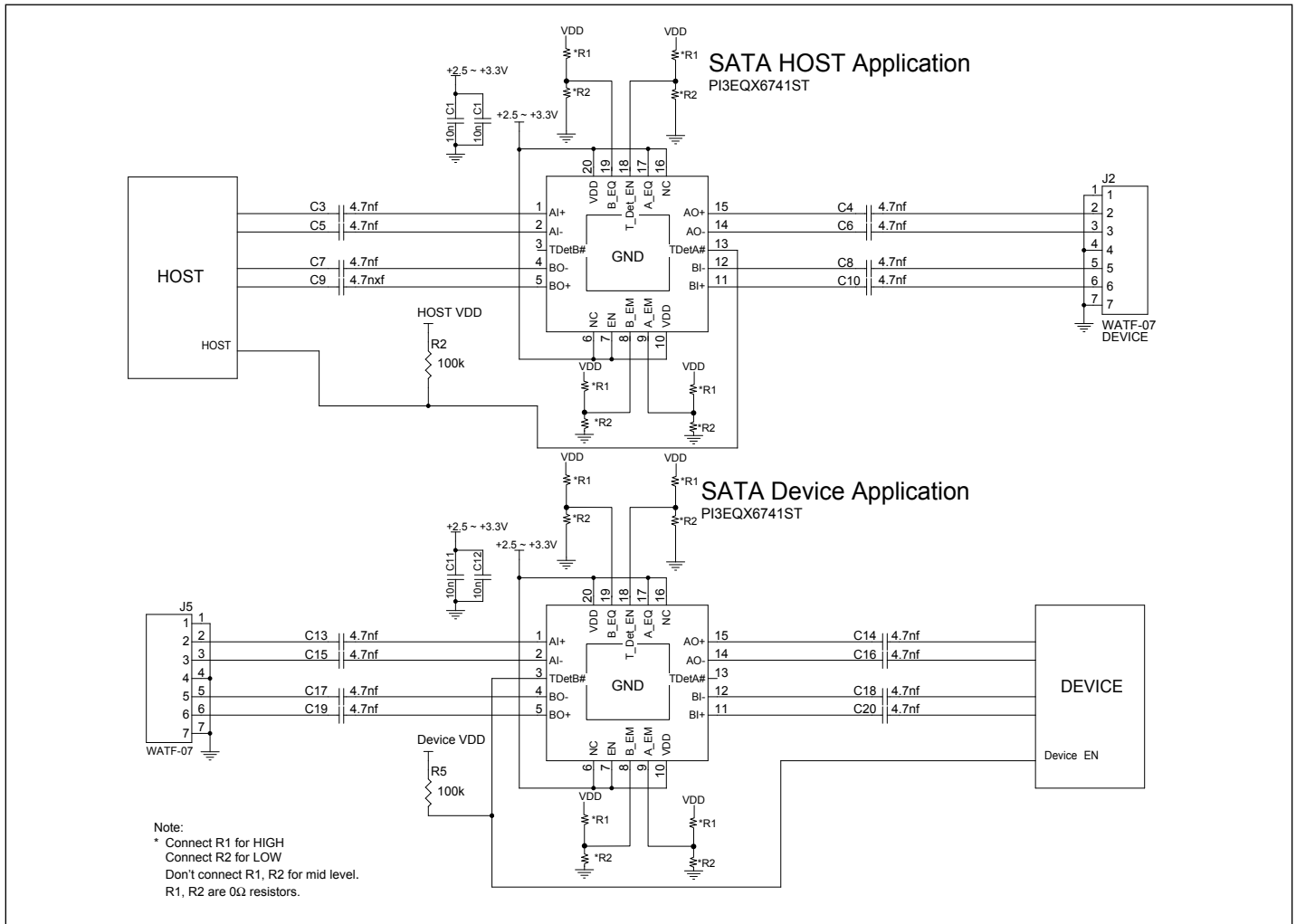and Differential Voltage Peak-to-Peak**

Pre-emphasis = $20 \cdot Log(V_{DIFF-PRE}/V_{DIFF})$
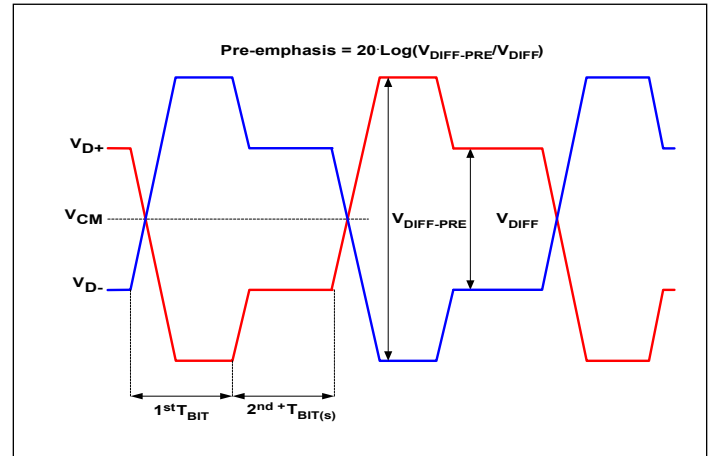
Definition of Pre-emphasis

FR4
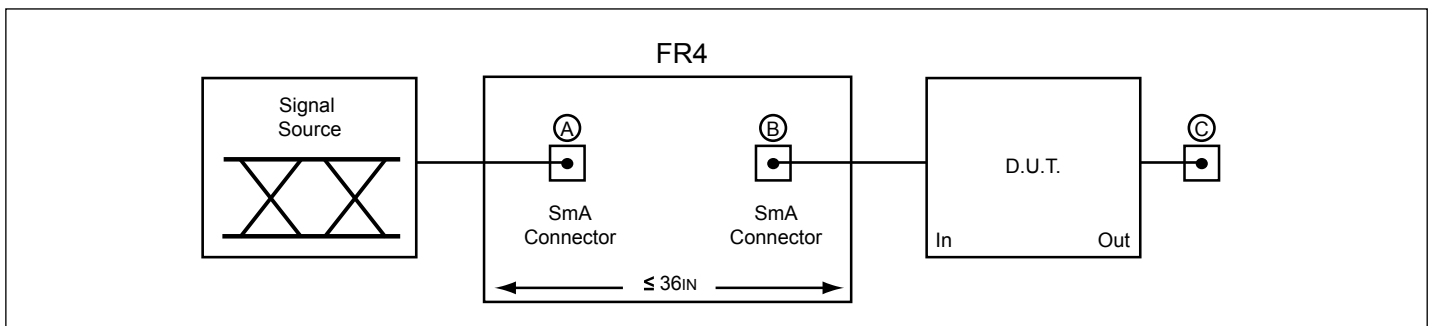
Test Condition Referenced in the Electrical Characteristic Table

Auto Slumber Mode Entry and Exit Timing

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Application Schematic

SATA HOST Application
PI3EQX6741ST

SATA Device Application
PI3EQX6741ST

Note:
* Connect R1 for HIGH
Connect R2 for LOW
Don't connect R1, R2 for mid level.
R1, R2 are 0Ω resistors.

Packaging Mechanical: 20-contact TQFN (ZD)

NOTE :
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS. COPLANARITY SHALL NOT EXCEED 0.08 mm.
3. WARPAGE SHALL NOT EXCEED 0.08 mm.
4. REFER JEDEC MO−220.

PERICOM Semiconductor Corporation	**DATE: 09/11/08**
DESCRIPTION: 20-Lead, Thin Fine Pitch Quad Flat No-Lead (TQFN)	
PACKAGE CODE: ZD20	
DOCUMENT CONTROL #: PD-2084	**REVISION: --**
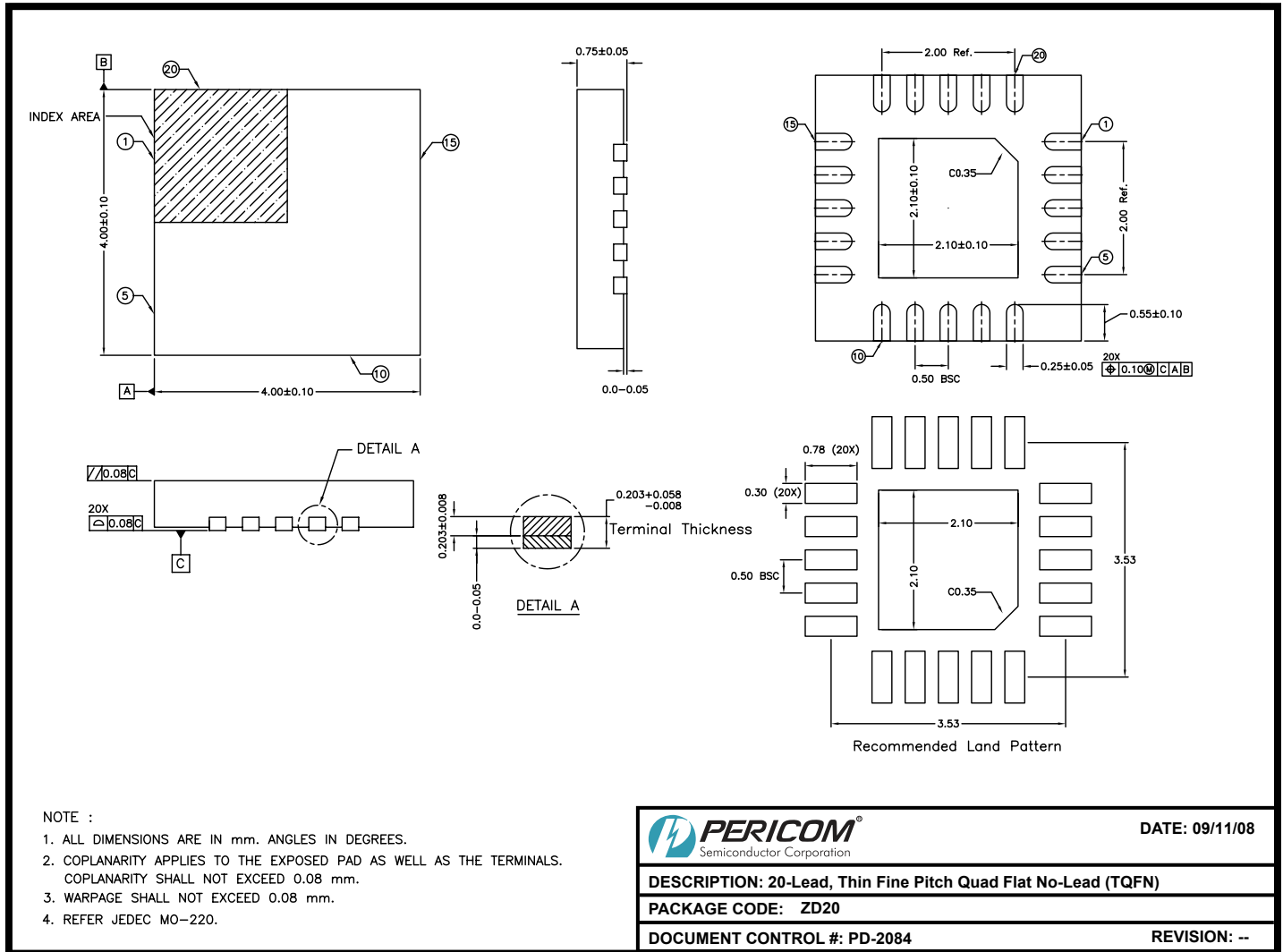
08-0456

Note: For latest package info, please check: http://www.pericom.com/support/packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Number	Package Code	Package Description
PI3EQX6741STZDE	ZD	20-Lead, Thin Fine Pitch Quad Flat No-Lead (TQFN)
PI3EQX6741STZDEX	ZD	20-Lead, Thin Fine Pitch Quad Flat No-Lead (TQFN), Tape & Reel

Notes:

- Thermal characteristics can be found on the company web site at www.pericom.com/packaging/

- E = Pb-free and Green

- X suffix = Tape/Reel

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